Requester Item Number	assembly with low ig responsibility.	Note: if the item is an assemb acturer has engineering respo	n. Note: ufacture	rer listed iter thich the ma	thin the manufacture evel materials for wh	ances wit lower le	n of the substa compasses all	is a declaration en	This documen level parts, the	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					
Company name* Company unique ID Unique ID Authority Response Date*  2023-06-08  Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Enviro Compliance NA Product-Enviro Compliance NA Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards@onsemi.org Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 Seconds 3		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					*	IPC Web Site for Information on IPC-1752 Standard Form Type				752-21.1			
Contact Name  Title - Contact  Product Enviro Compliance  NA  Product-Env-Stewards  Authorized Representative*  Product-Env-Stewards  Product Enviro Compliance  NA  Product-Env-Stewards@onsemi.  Title - Representative  Phone - Representative*  Phone - Representative*  Phone - Representative*  Product-Env-Stewards@onsemi.  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Effective Date  Version  Manufacturing Site  Weight*  UOM  Manufacturing Proccess Information  Terminal Plating / Grid Array Material  Terminal Plating / Grid Array Material  Terminal Base Alloy  Precious metal (e.g. Ag,Au, NiPdAu) (no  CU Alloy  NA  O  C 30  seconds 3														mation	Supplier Info
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Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.on  Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  GBPC3510W BR GBPCW GPPN 35A 1000V 2023-06-08 TSCBE 16949.998 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3			3	2023-06-0											nsemi
Authorized Representative*  Product-Env-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Manufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  Precious metal (e.g. Ag,Au, NiPdAu) (no  CU Alloy  NA  Phone - Representative*  Phone - Representative*  NA  Product-Env-Stewards@onsemi.  Manufacturing Site  Version  Manufacturing Site  Weight*  UOM  16949.998  mg  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Compliance  Na  Peak Process Body Temperature  Number of Reflow Compliance  Na  Peak Process Body Temperature  Number of Reflow Compliance  Na  Version  Manufacturing Site  Weight*  UOM  Na  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  Manufacturing Site  Weight*  Vomber of Reflow Compliance  Na  Version  Manufacturing Site  Version  M		act*		Phone - Contact*			Pł	Title - Contact					Contact Name		
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Requester Item Number		esentative*		Phone - Representative*			sentative	orized Representative*  Title - Representative							
GBPC3510W   BR GBPCW GPPN 35A 1000V   2023-06-08   TSCBE   16949.998   mg	Product-Env-Stewards@onsemi.com			NA NA			N	Product Enviro Compliance				vards	Product-Env-Ste		
Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow C Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	Unit Type	ht* UOM	eight*	W	nufacturing Site	Mai	Version	ffective Date	E		Mfr Item Name	em Number	Mfr Ite	ter Item Number	Reque
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	ycles	Number of Reflow Cycles	k Temperature Number of Reflow Cy		Body Temperature Max Time at Peak		ss Body Tempe	Peak Process Boo		al Base Alloy J-STD-020 MSL Ra		Terminal Base	erminal Plating / Grid Array Material Termin		Termin
(Sn)		3	3	seconds	30		C	0		CU Alloy NA		CU Alloy	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		
Comments															Comments

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the p contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and bel as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state law the tast implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable t										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature R		,								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg